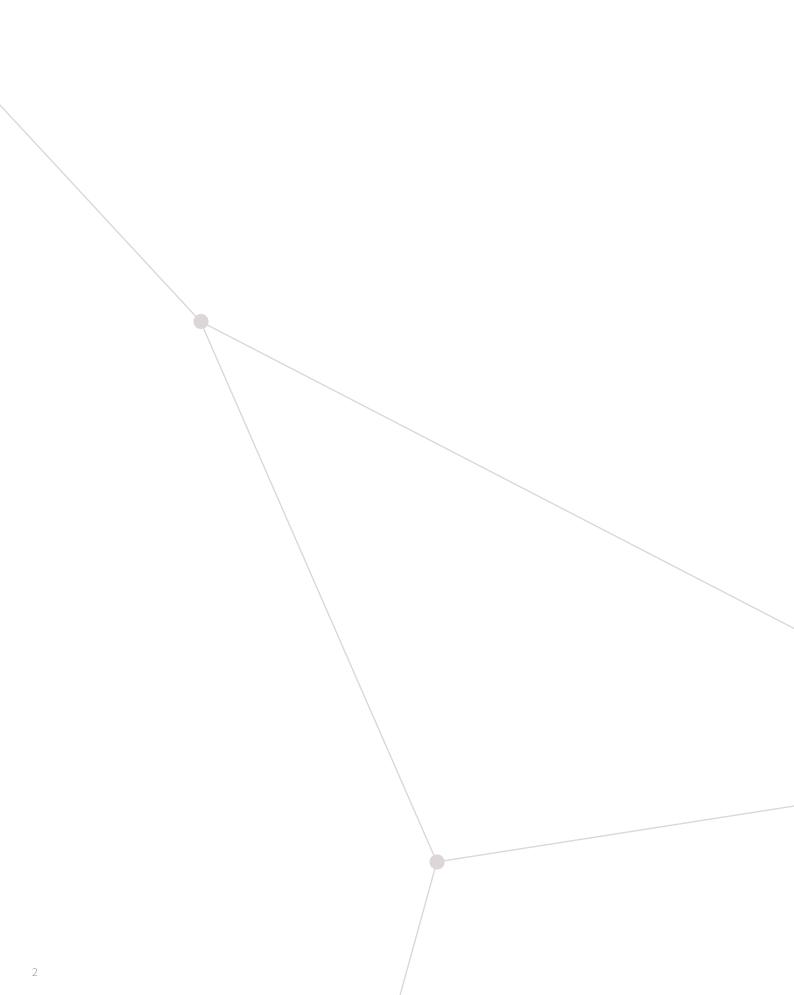


Industrial and general purpose gate driver ICs

Selection guide 2017





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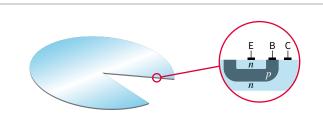
Infineon gate driver IC technologies

Leveraging the application expertise and advanced technologies of Infineon and International Rectifier, the industrial and general purpose gate driver ICs are well suited for many application such as major home appliances, industrial motor drives, solar inverters, UPS, switched-mode power supplies, and high-voltage lighting. Infineon offers a comprehensive portfolio with a variety of configurations, voltage classes, isolation levels, protection features, and package options.

These flexible gate driver ICs are complementary to Infineon IGBTs, silicon and silicon carbide MOSFETs (CoolMOS™ and CoolSiC™), or as part of integrated power modules. Every switch needs a driver.



Level-shifting p-n junction isolation (LS-JI) technology is a mature, proven industry standard MOS/CMOS fabrication technique. Infineon's proprietary HVIC and latch-immune CMOS technologies enable ruggedized monolithic construction. The advanced process allows monolithic high-voltage and low-voltage circuitry construction with the best price per performance.

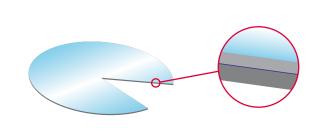


Main benefits of JI technology:

- > High current capability
- > Precision analog circuitry (tight timing/propagation delay)
- > Most comprehensive portfolio with industry-standard gate drivers
 - Voltage classes: 1200 V, 700 V, 600 V, 200 V, and 100 V
- Configurations: three-phase, half-bridge, single channel, and more
- > Drivers tailored towards the best price per performance



Level-shifting silicon-on-insulator (LS-SOI) technology is an advanced fabrication technique used for Infineon EiceDRIVER™ SOI products. The silicon is separated from the substrate by a buried oxide layer. The top layer, which is the silicon film, is used to produce the transistor. The bottom layer is used as the silicon substrate. The buried silicon dioxide provides an insulation barrier between the active layer and silicon substrate. The advanced process allows monolithic high-voltage and low-voltage circuitry construction with additional technology-enhanced features.



Main benefits of Infineon SOI technology:

- Best-in-class immunity to negative transients prevents erratic operation and latch-up while improving reliability
- > Low-ohmic integrated bootstrap diode has the lowest reverse recovery losses resulting in reduced power losses
- Minimum level-shift losses improve driver efficiency and allows flexible housing designs
- > 600 V and higher withstand voltages for operating margin
- Integrated filters



Coreless transformer (CT) technology is an isolated technology which uses semiconductor manufacturing processes to integrate an on-chip transformer consisting of metal spirals and silicon oxide insulation. These coreless transformers are used for transmitting switching information between input chip and output chip. Two isolated chips ensure galvanic isolation.



Main benefits of CT technology:

- > Galvanic isolation
- > Allows very large voltage swings of ±1200 V or larger
- > Immunity against negative and positive transients
- > Increases reliability of the end product
- > Low losses and low power dissipation



Non-isolated (NI) technology refers to gate drivers utilizing low-voltage circuitry. Infineon's world-class fabrication techniques enable high-current gate drivers for high-power-density applications in industry standard DSO-8 and small form-factor SOT23 and WSON packages.

Typical applications



Level-shifting technology (LS-SOI) & (LS-JI)



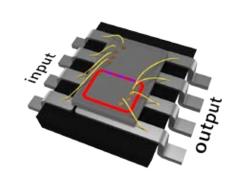
Coreless transformer (CT) technology



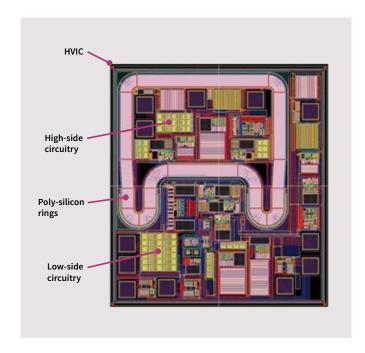


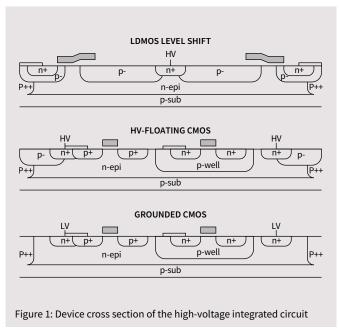
Junctional isolation technology

Pioneered by International Rectifier since 1984 with the introduction of the first monolithic product, the high-voltage integrated circuit (HVIC) technology uses patented and proprietary monolithic structures integrating bipolar, CMOS, and lateral DMOS devices with breakdown voltages above 700 V and 1400 V for operating offset voltages of 600 V and 1200 V. Using this mixed signal HVIC technology, both high-voltage level-shifting circuits and low-voltage analog and digital circuits can be implemented. With the ability to place high-voltage circuitry (in a 'well' formed by polysilicon rings) that can 'float' 600 V or 1200 V on the same silicon away from the rest of the low-voltage circuitry, high-side power MOSFETs or IGBTs that exist in many popular off-line circuit topologies such as buck, synchronous boost, half-bridge, full-bridge and three-phase.



These HVIC gate drivers with floating switches are well suited for topologies requiring high-side and bridge configurations.





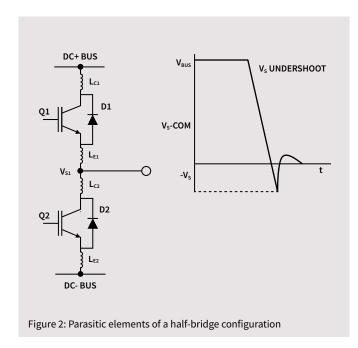
Infineon SOI technology

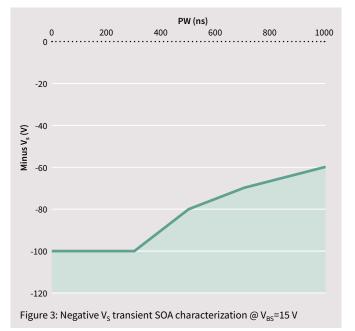
EiceDRIVER™ products with Infineon SOI technology provide unique, measurable, best-in-class advantages.

Negative V_S transient (-V_S) operation robustness

Today's high-power switching converters carry a large load current. The V_s voltage swing does not stop at the level of the negative DC bus. It swings below the level of the negative DC bus due to the parasitic inductances in the power circuit and from the die bonding to the PCB tracks. This undershoot voltage is called "negative V_s transient".

High-voltage EiceDRIVERTM products using Infineon SOI have the best-in-the-industry operational robustness. In Figure 3, the safe operating line is shown at $V_{BS} = 15 \text{ V}$ for pulse widths up to 1000 ns. Above this line, the products do not show unwanted functional anomalies or permanent damage to the IC.

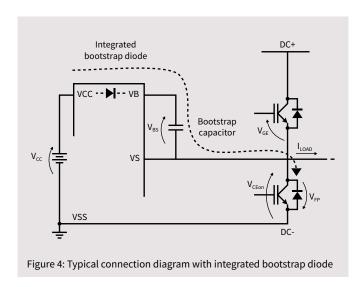






Integrated bootstrap diode

The bootstrap power supply is one of the most common techniques for suppling power to the high-side driver circuitry due to its simplicity and low cost. As shown in Figure 4, the bootstrap power supply consists of a bootstrap diode and capacitor. The floating channel of JI drivers is typically designed for bootstrap operation. Infineon SOI drivers features excellent ultra-fast bootstrap diodes. The low diode resistance of $R_{BS} \leq 40~\Omega$ enables a wide control range. The Infineon SOI drivers with this feature can drive larger IGBTs without the risk of self-heating, minimize BOM count, and reduce system cost.



Level shift losses

Level-shift losses can be a very significant part as the operating frequency increases. A level-shift circuit is used to transmit the switching information from the low-side to the high-side. The necessary charge of the transmission determines the level-shift losses. EiceDRIVER™ high-voltage products using the Infineon SOI technology requires

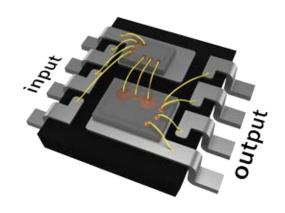
a very low charge to transmit the information. Minimizing level-shifting power consumption allows design flexibility of higher frequency operations, as well as longer lifetime, improved system efficiency and application reliability.

Infineon CT Isolation Technology

Infineon EiceDRIVER™ galvanically isolated products use the magnetically-coupled coreless transformer (CT) technology to provide signal transfer across the galvanic isolation. The technology provides short propagation delay, excellent delay matching, and strong robustness. The isolation allows very large voltage swings (e.g. ±1200 V).

Robustness

- > Extremely robust signal transfer independent of common mode noise
- > Stability against common mode noise up to 100 V/ns
- Tight propagation delay matching: Tolerance improves application robustness without variations due to age, current, and temperature

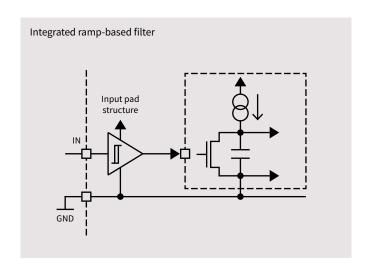


Design flexibility

- > Wide range of gate voltages including negative gate voltage
- > CT technology is ready for use with silicon carbide MOSFETs
- Closed-loop gate current control option

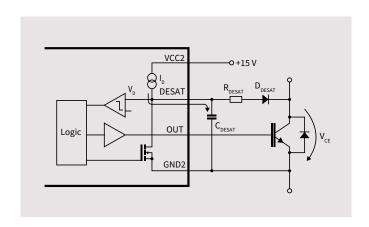
Precise timing control

- Precise integrated filters reduce the propagation delay and propagation delay variation over a wide range of operating conditions
- > Integrated filters reduce the effort for external filters
- Tight propagation delay allows minimum deadtime and improved system efficiency



Protection

- Short dead times with tight propagation delay matching and precise integrated filters over a wide range of operating conditions
- Fast short-circuit shut down using optional fast DESAT detection and two-level turn-off for short-circuit current protection
- Reliable short-circuit detection via a fast and accurate desaturation (DESAT) detection circuit protects the power switches from damage during short-circuit condition
- Active miller clamping option protects against parasitic turn-on due to high dV/dt
- Built in short-circuit clamping limits the gate drive voltage during short circuit and lowers collecter voltage overshoot



Coupling method	Tolerance I _D	Tolerance V _D
Coreless transformer	±10%	-8/+6%
Capacitive	±18%	-8/+6%
Optical	-48/+32%	±11%

Safety certification

> Safety certification available for VDE0884 and UL1577





For SiC MOSFET switching

- > Ideal for ultra-fast switching 1200 V silicon carbide power transistors such as CoolSiC™ MOSFETs
- > The drivers incorporate most important key features and parameters for SiC driving:
 - Tight propagation delay matching
 - Precise input filters

- Wide output side supply range
- Negative gate voltage capability
- Extended common mode transient immunity (CMTI) capability

Silicon carbide drive requirements

CoolSiC™ MOSFETs and modules

Infineon's CoolSiC™ silicon carbide (SiC) MOSFETs open new degrees of freedom for designers to improve efficiency and system flexibility.

The CoolSiC™ MOSFET offers advantages of the lowest gate charge and device capacitance levels in 1200 V switches, no reverse recovery losses of the internal body diode, temperature-independent low switching losses, and threshold-free on-state characteristics. Infineon's unique 1200 V SiC MOSFET adds additional advantages of superior gate-oxide reliability enabled by state-of-the-art trench

design, best in class switching and conduction losses, highest transconductance (gain), full turn-on capability with gate voltage of only +15 V and short-circuit robustness.

The result is a robust SiC MOSFET which is ideal for hardand resonant-switching topologies. It can be driven like an IGBT using standard drivers delivering the highest level efficiency at switching frequencies unreachable by Si based switches allowing for system size reduction, higher power density and improved lifetime reliability.

Lead products					
Schematic		Туре	R _{DSON}	V _{DS}	Package
Single switch	Gate Source	IMW120R045M1	45 mΩ	1200 V	TO-247-3pin
Single switch	Gate Power Source	IMZ120R045M1	45 mΩ	1200 V	TO-247-4pin
Booster with NTC		DF11mR12W1M1_B11	11 mΩ	1200 V	Easy 1B
		DF23mR12W1M1_B11	23 mΩ	1200 V	-11-11-11-11-1
Half bridge with NTC		FF11mR12W1M1_B11	11 mΩ	1200 V	O a labour 12 o
		FF23mR12W1M1_B11	23 mΩ	1200 V	

Sampling on request

Recommended gate drivers

Ultra-fast switching 1200 V power transistors such as CoolSiC™ MOSFETs can be easier handled by means of isolated gate output sections. Therefore, the following galvanically isolated EiceDRIVER™ ICs based on Infineon's coreless transformer technology are recommended as most suitable. For a larger selection of isolated gate

drivers, please refer to the product portfolio overview section of the selection guide. The drivers incorporate most important key features and parameters for SiC driving such as tight propagation delay matching, precise input filters, wide output-side supply range, negative gate voltage capability, and extended CMTI capability.

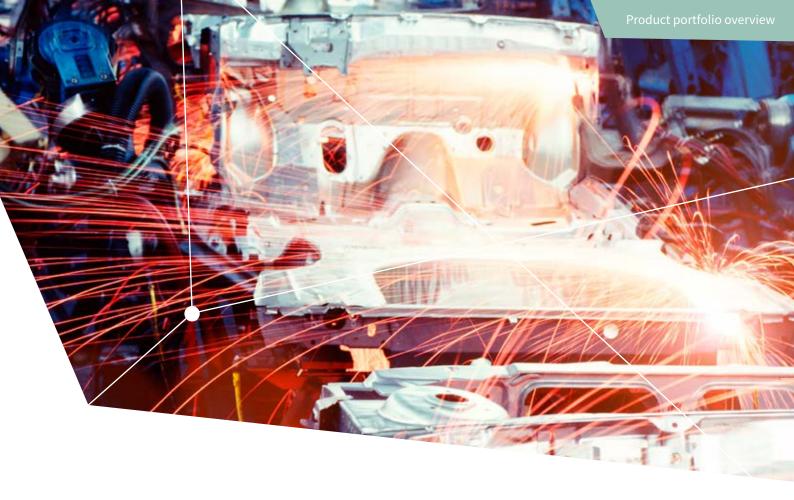
Recommended ga	ate drivers								nctional plation DSO-8 150 mil DSO-8 150 mil DSO-8 300 mil DSO-8 300 mil DSO-16 DSO-16 DSO-36 DSO-36 DSO-36 DSO-36 DSO-36 DSO-36 DSO-36 DSO-36 DSO-36				
Product	Part number	Typ. peak drive current	VCC2- VEE2	Typ. prop. delay	Typ.	UVLO OFF	Miller clamp	Other key features	Package				
1EDI compact isolated	1EDI20N12AF	3.5 A	40.0 V	≤ 120 ns	9.1 V	8.5 V	No	Functional	circuit bing; T protection; e shutdown DSO-8 150 mil in				
high-side driver family	1EDI60N12AF	9.4 A	40.0 V	≤ 120 ns	9.1 V	8.5 V	No	isolation					
	1EDI20I12MF	3.5 A	20.0 V	≤ 300 ns	11.9 V	11.0 V	Yes		eepage DSO-8 300 mil recuit g; rrotection; nutdown DSO-36 g; rrotection, or off shut wo-level				
	1EDI20H12AH	3.5 A	40.0 V	≤ 125 ns	12.0 V	11.1 V	No	8 mm creepage	DSO-8 300 mil				
	1EDI60H12AH	9.4 A	40.0 V	≤ 125 ns	12.0 V	11.1 V	No	clearance					
	1EDI20I12MH	3.5 A	20.0 V	≤ 300 ns	11.9 V	11.0 V	Yes						
1ED-F2 isolated high-side driver with integrated protection	1ED020I12-F2	2.0 A	28.0 V	≤170 ns	12.0 V	11.0 V	Yes	Short circuit clamping; DESAT protection; active shutdown	DSO-8 150 mil DSO-8 300 mil DSO-16 On; DSO-36 On; ut				
2ED-F2 isolated dual high-side driver with integrated protection	2ED020I12-F2	2.0 A	28.0 V	≤170 ns	12.0 V	11.0 V	/ Yes Short circuit clamping; DESAT protection; active shutdown		DSO-36				
1ED slew rate control (SRC) isolated high-side driver	1EDI20I12SV	2.0 A	28.0 V	≤ 485 ns	11.9 V	11.0 V	Yes	Real-time adjustable gate current control; over-current protection, soft turn-off shut down, two-level turn-off	DSO-8 300 mil DSO-16 DSO-36				

Product portfolio overview

Infineon's gate driver IC solutions are the expert's choice. With more than 200 reliable and efficient gate driver solutions, we provide a comprehensive portfolio for virtually any application. To ease the selection process, this overview is structured along the configurations of the gate driver ICs, as opposed to by application topology.

Half-b	lalf-bridge gate driver ICs																										
Typical co	onnection																										
V _{cc} o-	- N									qe		e e	_		Separate pin for logic ground	_		N									
v _{cc}	Ĭ _	Up to 12	200 V				ion			dio	on	tim	NO.		gro	ctio		tdo	¥								
	VCC VE	³┡ <u>╅</u>	\neg	>			tect			rap	ecti	ead	nutd		ogic	ote		shu	Skor								
INo-	TIN H		<u> </u>	golo		ifier	pro		₽0	otst	prot	le d	lest	۵۵	Forl	h pr		ent	ol e								
SD o -	SD VS		To load	Technology	Ö	ldm	ion		ortir	d bo	ent	nab	nab	atin	pin	ong	_	cnu	ltag								
	COM LC			Tec	ara	nt a	urat	a	repo	ate	curr	amr	amr	scill	ate	÷thr	OWI	ver-	٥٨-		4	8		~ +	-24	-14	
	Ţ	-			Comparator	Current amplifier	Desaturation protection	Enable	Fault reporting	Integrated bootstrap diode	Over-current protection	Programmable dead time	Programmable shutdown	Self-oscillating	par	Shoot-through protection	Shutdown	Soft over-current shutdown	Under-voltage lockout	DSO-8	DSO-14	DSO-18	DIP-8	DIP-14	SSOP-24	VQFN-14	CHIP
					Ŭ	ರ	۵	ш	Fe	드				Š	Š	S	ठ	Š	5	ă	ă					>	٥
Voltage class [V]	I _{O+} /I _{O-} typ [mA]	Typ. prop. delay: off/on [ns]	Base PN							(:		atuı pag	res e 24	.)									Pack e pa				
1200	1500/2500	85/85	2ED020I12-FI	СТ	✓	✓										✓	✓		✓			✓					
	2000/3000	440/440	IR2214	JI			✓		√						✓	√		✓	✓						√		
700	78/169	220/220	IR7304	JI												✓			✓	√							
	1900/2300	270/680	IR7184	JI												✓	✓		✓	√							
650	1500/2500	85/85	2ED020I06-FI	СТ												√	✓		✓			✓					
	78/169	220/220	IR2304	JI												√			✓	√			√				
	,	,	IR25601	JI												√			✓	✓							
			IR21531	JI									√	✓		✓	✓		✓	√			✓				√
	180/260	na	IR21531D	JI 						√			√	√		√	✓		√				√				
		-	IR25603	JI 						,			√	√		√	√		√	√			√				,
			IRS2153(1)D	JI						√			✓	√		√	✓		√	√			√				√
		-	IR2108 IR21084	JI								√			√	✓			✓ ✓	V	/		V	✓			
		200/220	IR21064 IR2308	JI								V			V	✓			✓	√	V		√	V			
			IR25606	JI												✓			✓	✓			V				
	200/350		IR2109	JI												√	√		√	✓			√				
			IR21091	JI								√				√	√		✓	✓			✓				
		200/750	IR21094	JI								√			√	✓	√		✓		1			√			
600			IR2302	JI												√	√		√	V			✓				
			IR2103	JI												√			✓	✓			√			П	
	210/360	150/680	IR2104	JI												√	✓		✓	√			✓				
			IR25602	JI												√	√		✓	✓						П	
	220/480	500/500	IRS2890D*	JI					✓	✓	✓					✓			✓		✓						
	250/500	150/750	IR2111	JI												✓			✓	✓			✓				
		150/150	IRS2304	JI												✓			✓	✓			✓				✓
		150/680	IRS2103	JI												✓			✓	✓			✓			Ш	✓
		130/000	IRS2104	JI												✓	✓		✓	✓			✓				✓
	290/600	150/750	IRS2111	JI												✓			✓	✓			✓				√
	250,000		IRS2108	JI												✓			✓	√			✓				✓
		200/220	IRS2308	JI												√			✓	√			✓				✓
			IRS21084	JI								√			✓	√			✓		√			✓			
		200/750	IRS2109	JI												✓	✓		✓	✓			✓				✓

^{*}New



Half-bridge gate driver ICs Typical connection Separate pin for logic ground Soft over-current shutdown Integrated bootstrap diode Shoot-through protection V_{cc}o Programmable dead time Programmable shutdown Up to 1200 V Desaturation protection Over-current protection Under-voltage lockout VCC ۷B **Current amplifier** INo НО Self-oscillating Fault reporting SD $\overline{\mathsf{SDo}}$ ۷S **o**To load Comparator Shutdown SSOP-24 СОМ DSO-18 Enable DSO-14 **DSO-8** DIP-8 DIP-14 Voltage class [V] Typ. prop. delay: off/on [ns] Package (see page 25) l_{o+}/l_{o−} typ [mA] **Features** Base PN (see page 24) 300/310 2EDL05N06P SOI **√** | **√** \checkmark ✓ 360/700 ✓ 400/420 2EDL05I06P SOI ✓ ✓ IRS2183 JI √ √ \checkmark ✓ ✓ JI 220/180 IR2183 ✓ ✓ ✓ ✓ IR(S)21834 J١ ✓ √ \checkmark ✓ 1900/2300 J١ IRS2184 \checkmark \checkmark ✓ \checkmark \checkmark \checkmark 600 JI IR2184 \checkmark ✓ ✓ \checkmark 270/680 IR21844 J١ \checkmark \checkmark \checkmark \checkmark IRS21844 JI \checkmark ✓ \checkmark ✓ \checkmark \checkmark \checkmark 2000/3000 440/440 IR2114 JI ✓ ✓ ✓ ✓ **√** ✓ **√** 300/310 SOI ✓ **√** ✓ ✓ ✓ ✓ 2EDL23N06P 2300/2800 SOI **√ √ √** ✓ ✓ ✓ 400/420 2EDL23I06P JI IRS2003 ✓ ✓ JI ✓ 200 290/600 150/680 IRS2008* ✓ JI IRS2004

^{*}New

Three-phase gate driver ICs Typical connection DC+ bus HIN Separate pin for logic ground LIN Integrated bootstrap diode ΕN Output for brake chopper Desaturation protection Over-current protection VB (x3) Under-voltage lockout FAULT HO (x3) Current amplifier RCIN VS (x3) Fault reporting ITRIP LO (x3) **DSO-20 WB** DSO-28 WB VSS СОМ MQFP-64 TSSOP-28 VQFN-34 Enable DIP-28 LCC-32 CHIP DC- bus Voltage class [V] Typ. prop. delay: off/on [ns] **Features** Package Base PN typ [mA] (see page 25) (see page 24) IR2233 JI ✓ **√ √ √** V V ✓ \checkmark ✓ \checkmark 250/500 700/750 1200 JI ✓ ✓ \checkmark \checkmark IR2235 \checkmark √ \checkmark \checkmark 550/550 ✓ **√** 350/450 IR2238 JI ✓ ✓ ✓ \checkmark \checkmark ✓ **√** 6ED003L06-F2 SOI ✓ ✓ √ √ ✓ √ 490/530 165/375 \checkmark ✓ ✓ ✓ \checkmark ✓ 6EDL04I06(N,P) SOI ✓ \checkmark ✓ ✓ ✓ 530/530 6EDL04N06P SOI \checkmark √ \checkmark IR2136 J١ \checkmark \checkmark \checkmark ✓ \checkmark \checkmark IR21363 J١ √ ✓ √ ✓ ✓ √ ✓ 400/425 IR21365 J١ ✓ ✓ ✓ ✓ ✓ ✓ JI ✓ ✓ **√** √ IR21368 ✓ ✓ 530/500 IR21364 J١ ✓ \checkmark \checkmark \checkmark ✓ \checkmark 200/350 600 IRS2334 J١ \checkmark \checkmark IRS2336 J١ \checkmark √ \checkmark ✓ \checkmark 530/530 IRS2336D JI ✓ ✓ ✓ ✓ ✓ ✓ ✓ ✓ ✓ √ IRS23364D JІ ✓ ✓ ✓ ✓ ✓ ✓ ✓ ✓ ✓ J١ √ ✓ ✓ √ ✓ ✓ IRS23365D √ **√** 425/675 IR213(0,2) J١ ✓ ✓ ✓ ✓ \checkmark ✓ ✓ \checkmark JI √ \checkmark ✓ ✓ 300/1300 IR2131 \checkmark 250/500 IR2133 JI √ \checkmark \checkmark \checkmark \checkmark 700/750 IR2135 JI \checkmark ✓ \checkmark \checkmark \checkmark ✓ \checkmark \checkmark 490/530 6ED003L02-F2 SOI √ \checkmark √ ✓ ✓ ✓

200

165/375

530/530

6EDL04N02P

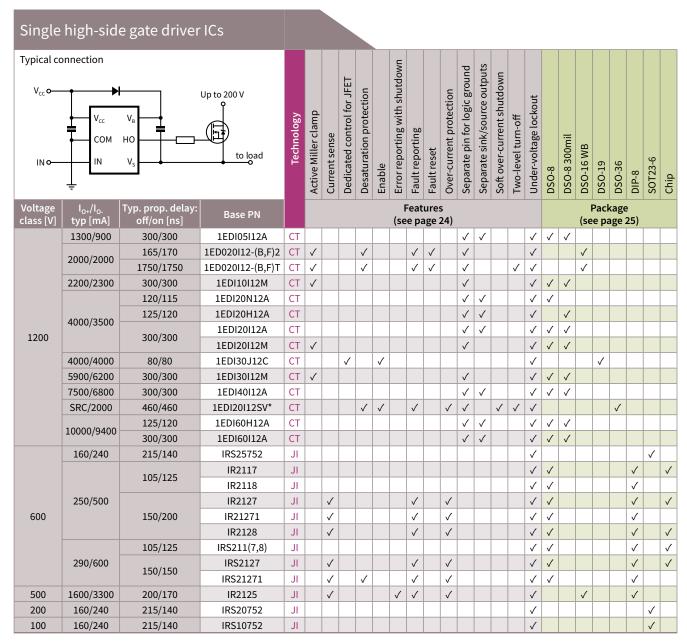
SOI

✓

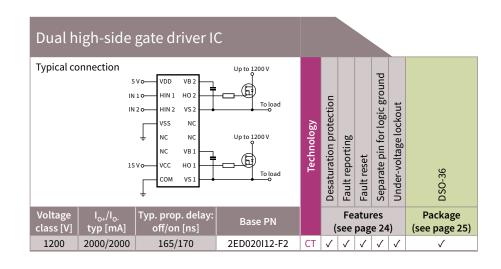
√ ✓

✓

✓

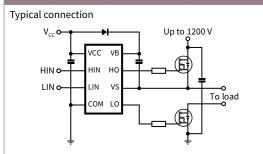


SRC = Turn on slew rate control *New



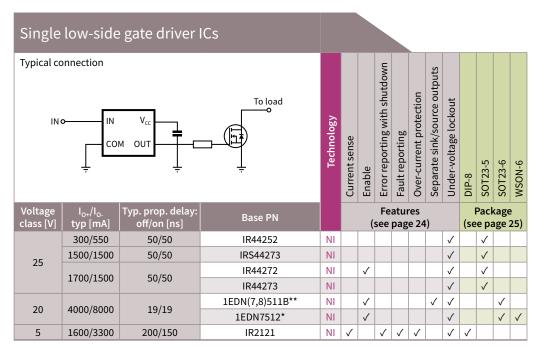


High-side and low-side gate driver ICs

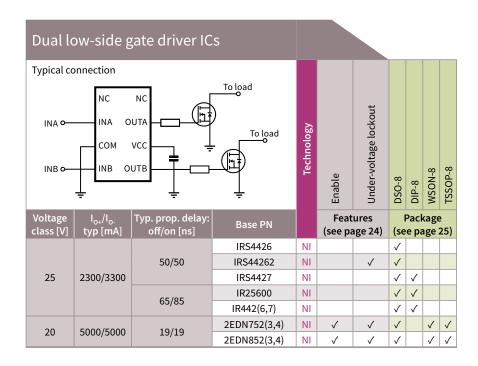


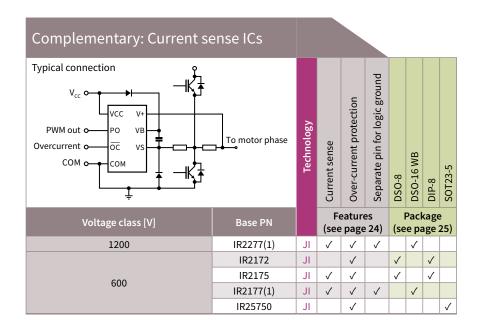
Technology	Integrated bootstrap diode	Separate pin for logic ground	Shutdown	Under-voltage lockout	DSO-8	DSO-14	DSO-16 WB	DIP-8	DIP-14	VQFN-14	CHIP

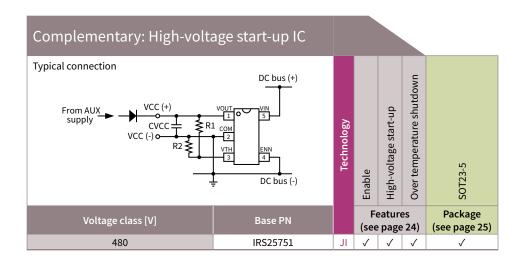
Voltage class [V]	l _{o+} /l _{o-} typ [mA]	Typ. prop. delay: off/on [ns]	Base PN				ure age		Package 4) (see page 25)						
1200	2000/2500	225/280	IR2213	JI		✓	✓	✓			✓		✓		✓
700	220/350	200/220	IR7106	JI				✓	✓						
			IR2106	JI				✓	✓			✓			
			IR21064	JI		✓		✓		✓			✓		
	200/350	200/220	IR2301	JI				✓	✓			✓			
			IR25604	JI				✓	✓						
			IRS2301	JI				✓	✓						
	210/360	150/160	IR2101	JI				✓	✓			✓			✓
	210/360	150/160	IR2102	JI				✓	✓			✓			
	250/500	105/125	IR2112	JI			✓	✓			✓		✓		
		130/135	IRS2112	JI		✓	✓	✓			✓		✓		√
	200/600	150/160	IRS2101	JI				✓	✓			✓			✓
	290/600	200/220	IRS2106	JI				✓	✓			✓			√
600		200/220	IRS21064	JI		✓		✓		✓			✓		
	360/700	400/420	2EDL05I06BF	SOI	✓			✓	✓						
			IRS2181	JI				✓	✓			✓			✓
	1900/2300	220/180	IR2181	JI				✓	✓			✓			
	1900/2300	220/160	IR21814	JI		✓		✓		✓			✓		
			IRS21814	JI		✓		✓		✓			✓	✓	
		04/120	IR2113	JI		✓	✓	✓			✓		✓		√
	2500/2500	94/120	IR25607	JI		✓	✓	✓			✓				
		120/130	IRS2113	JI		✓	✓	✓			✓		✓	✓	✓
			IRS2186	JI				✓	✓			✓			√
	4000/4000	170/170	IRS21864	JI		✓		✓		✓			✓		
			IRS21867	JI				✓	✓						
500	2500/2500	94/120	IR2110	JI		✓	✓	✓			✓		✓		
500	2500/2500	120/130	IRS2110	JI		✓	✓	✓			✓		✓		√
	290/600	150/160	IRS2005	JI				✓	✓					✓	
200	1000/1000	60/60	IRS2011	JI				✓	✓			✓			✓
200	1000/1000	75/80	IR2011	JI				✓	✓			✓			
	3000/3000	65/95	IR2010	JI		✓	✓	✓			✓		✓		



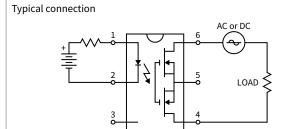
^{*}New **Coming soon







Complementary: Opto-isolated solid state relays



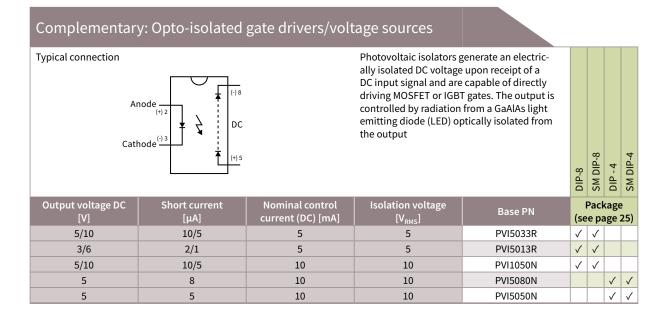
Microelectronic relays (MER) are power MOSFET or IGBT output photovoltaic relays where the output switch is controlled by radiation from a GaAlAs light emitting diode (LED) optically isolated from the output. MERs are a good choice to replace mechanical relays.

DIF -4-302	DIP-6	SM PDIP-6	DIP-8	SM DIP-8	DIP - 4	SM DIP-4	DIP-10

Load voltage [V]	Load current [mA]	$R_{DS(on)} \ [\Omega]$	Isolation voltage [V _{RMS}]	Base PN				Pacl e pa				
	1000 AC/DC		3750	PVX6012	✓							
	140 AC/DC	27/7	4000	PVU414		✓	✓					
400	120 AC/DC	35/9	4000	PVT412L	✓	✓						
400	240 AC/DC	6/2	4000	PVT412A		✓	✓					
	140 AC/DC	27/7	4000	PVT412		✓	✓					
	120 AC/DC	35	4000	PVT422				✓	✓			
	150 AC/DC	24	4000	PVA3354N						✓	✓	
300	150 AC/DC	24	4000	PVA3324N						✓	✓	
300	50 AC/DC	160	4000	PVA3055N						✓	✓	
	30 AC/DC	160	4000	PVA3054N						✓	✓	
	170 AC/DC	15/4.25	4000	PVT312L		✓	✓					
250	190 AC/DC	10/3	4000	PVT312		✓	✓					
250	170 AC/DC	8	4000	PVT322A				✓	✓			
	170 AC/DC	10	4000	PVT322				✓	✓			
200	150 AC/DC	24	4000	PVA2352N						✓	✓	
150	550 AC/DC	0.7/0.25	4000	PVT212		✓	✓					
	360 AC	5	1500	PVR130(0,1)								✓
	550 DC	1.5	4000	PVD1354N						✓	✓	
100	220 DC	1.5	4000	PVD1352N						✓	✓	
	27F AC/DC	5	4000	PVA1354N						✓	✓	
	375 AC/DC	5	4000	PVA1352N						✓	✓	
	1500 DC	0.25	4000	PVDZ172N						√	√	
	1000 AC	0.5	4000	PVAZ172N						√	✓	
60	1000 AC/2000 DC	0.5/0.15	4000	PVG613*		✓	✓					
	2000 AC/4000 DC	0.1/0.035	4000	PVG612A		✓	✓					
	1000 AC/2000 DC	0.5/0.15	4000	PVG612		✓	✓					
	2500 AC/4500 DC	0.1/0.04	4000	PVN013*		V	√					
20	4000 AC/6000 DC	0.05/0.015	4000	PVN012A		✓	✓					
	2500 AC/4500 DC	0.1/0.04	4000	PVN012		✓	✓					

^{*10} nA leakage current





Features

Addressing various application requirements, Infineon delivers solutions with an assortment of features intended to optimize performance, minimize size and reduce cost. Below is a table of additional gate driver IC features available in the current portfolio.

Feature	Benefits
Active Miller clamp	Protection against inadvertent dynamic turn-on because of parasitic effects
Brake chopper	Integrated brake IGBT driver with protection
Comparator	General purpose comparator included
Current amplifier	An independent opamp for current measurement or over-current detection
Current sense	Dedicated input detects over-current events
Dedicated JFET control	Optimized to drive SiC JFET
Desaturation protection	Protects the switch (IGBT) at short circuit
Enable	Dedicated pin terminates all outputs
Error reporting with shutdown	Pin indicates fault conditions and programs shutdown time
Fault reporting	Indicates an over-current or under-voltage shutdown has occurred
Fault reset	Dedicated pin resets the DESAT-FAULT-state of the chip
High-voltage start-up	Provides easy and fast circuit start-up while enabling low circuit standby losses
Integrated bootstrap diode	Integrated bootstrap reduces BOM
Over temperature shutdown	Internal over temperature protection circuit protects the IC against excessive power loss and overheating
Over-current protection	Ensures safe application operation in case of over-current
Programmable sead time	Dead time is programmable with external resistor for flexible design
Programmable shutdown	A shutdown feature has been designed into a pin
Self-oscillating	Integrated front end oscillator
Separate pin for logic ground	Dedicated pin or logic ground for improved noise immunity
Separate sink/source outputs	Simplifies gate resistor selection, reduces BOM, and improves dV/dt control
Shoot-through protection	Functionality such as deadtime and interlock
Shutdown	Dedicated pin disables the IC outputs
Soft over-current shutdown	Dedicated pin turns off the desaturated transistor, preventing over-voltages
Two-level turn-off	Lowers VCE overshoots at turn off during short circuits or over current events
Under-voltage lockout	Ensures safe application operation by avoiding unexpected driver behavior

Package options

Infineon offers a multitude of packages. Below is a list of gate driver IC package options which are currently available.





New product highlights

The following segment features Infineon's latest gate driver IC families at a glance. Visit the family pages for more information.

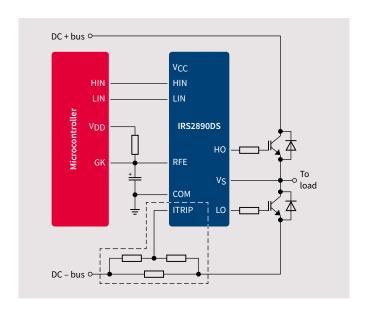
IRS2890DS 600-V gate driver IC

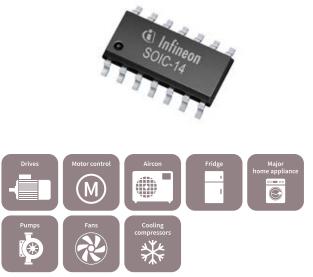
600-V half-bridge driver IC with overcurrent protection

The new 600-V half-bridge driver IC is optimized for high-voltage motor drive applications in major home appliance applications requiring rigorous standards for reliability and quality.

Designers are constantly challenged with developing compact, energy-efficient solutions while maintaining a high level of reliability and ruggedness. The IRS2980DS is tailored for motor drive applications requiring over current protection and best-in-class default reporting accuracy in a small form-factor with high-voltage IC process to realize a compact, efficient and robust monolithic construction while integrating several features.

The IRS890DS achieves high-power density by integrating the bootstrap FET, under-voltage (UVLO) protection, shoot-through protection, overcurrent protection, fault reporting, and fault clear function. The overcurrent protection feature has an internal threshold of $\pm 5~\%$ for accurate reporting. Additionally, the IRS2890DS has $\rm V_s$ operational logic of -8 V and is tolerant to negative transient voltages. The IRS28990DS is offered in fourteen-pin SOIC and requires the use of less pins then comparable parts on the market.





For more information visit www.infineon.com/IRS2890DS

IRS200x 200-V gate driver family

Now including IRS2008

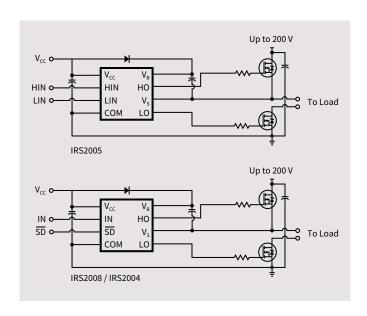
Infineon offers 200-V half-bridge and high- and low-side driver ICs tailored for low-voltage (24 V, 36 V, and 48 V) and mid-voltage (60 V, 80 V, and 100 V) motor drive applications.

The IRS200x family utilizes our advanced high-voltage IC process to realize a compact, efficient, and robust monolithic construction.

The IRS200x family consists of seven devices with a typical output sink current of 600 mA and typical output source current of 290 mA. The 200 V devices are 3.3, 5 and 15 V logic compatible. $V_{\rm CC}$ under-voltage lockout (UVLO) protection is a standard feature provided across the family while IRS2008 and IRS2005 also include $V_{\rm BS}$ UVLO

protection. Additionally, the IRS2008 has V_s operational logic of -8 V. The IRS2008, IRS2004, and IRS2003 include integrated deadtime and shoot-through protection. The 200 V devices feature low quiescent currents. IRS2008 and IRS2004 also features a shutdown input pin.

The 200 V devices are offered in eight-pin SOIC, eight-pin DIP or fourteen-pin 4 x 4 mm MLPQ packages with various logic input options and standard pin-out configurations for high design flexibility and fast time-to-market.





For more information visit www.infineon.com/200VHVIC

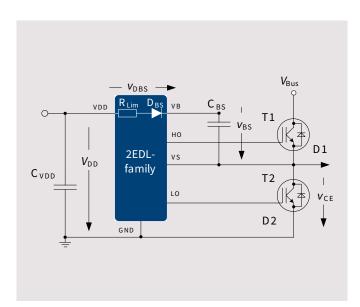
2EDL EiceDRIVER™ compact

600-V half-bridge gate driver ICs with integrated bootstrap diode

The new 2EDL EiceDRIVER™ Compact high-voltage gate driver family meets the ever-growing need for higher application efficiency and smaller form factors in consumer electronics and home appliances. It is optimized for the switching behavior and power losses of today's power supplies using IGBT and MOSFETs with dramatically reduced gate charges such as the latest generation of Infineon's CoolMOS™. With a monolithically integrated ultrafast low-ohmic bootstrap diode, the 2EDL Compact sets the benchmark for driver ICs needed in applications with more than 2 A output currents.

The 2EDL Compact family comprises seven 600 V drivers with output currents of 0.5 A and 2.3 A in DSO-8 and DSO-14 150 mil packages for applications based on IGBT or MOSFET switches:

- The 2EDL05I06BF in DSO-8, optimized for IGBTs, comes without interlock or dead time. It is ideal for switched reluctance motor drives and two-transistor forward switched-mode power supply topologies.
- > The 2EDL05I06PF in DSO-8 and the 2EDL05I06PJ in DSO-14 are optimized for IGBTs and include interlock and dead time. They are recommended for applications such as fans, pumps, major home appliances, power tools, and general purpose inverters. The DSO-14 version is recommended for industrial applications with higher creepage distance requirements.
- > The 2EDL05N06PF in DSO-8 and the 2EDL05N06PJ in DSO-14 boast the same features as the IGBT driver versions and an under-voltage lockout adapted for MOSFETs. They are recommended for servers and telecommunications equipment, low-voltage drives, e-bikes, battery chargers, and half-bridge-based switched-mode power supply applications.
- The 2EDL23I06PJ and 2EDL23N06PJ are 2.3 A half-bridge driver ICs in DSO-14 with interlock, dead time, fault enable, and overcurrent protection. The 2EDL23I06PJ for IGBTs is ideal for applications such as multi-oven IH cookers, fans, pumps, and drives. The 2EDL23N06PJ for MOSFETs is best suited for switched-mode power supplies, servers and telecommunications equipment, e-scooters, forklifts, and battery chargers.





For more information visit www.infineon.com/eicedriver-compact

1EDI20I12SV EiceDRIVER™

1200-V single-channel driver IC with dynamic slew-rate control

The new 1EDI20I12SV EiceDRIVER™ serves the latest generation of highly efficient low-EMI electric drive systems with a variety of advanced features. It is the first driver on the market with dynamic slew-rate control (SRC) that allows on-the-fly dV/dT control of electric drives through precise gate current control, providing for the best tradeoff between minimum power dissipation and minimum EMI depending on operating conditions such as high and low load.

The driver also includes desaturation protection for IGBTs and overcurrent protection for sense IGBTs via the fault status output pin. Two ready-state output pins indicate proper driver power supply and normal operation. Two-level turn-off with adjustable timing and voltage protects against excessive overvoltage in case of the IGBT operating at overcurrent or a short circuit. To turn on the IGBT, the driver works as an adjustable current source in conjunction with an external PMOS transistors and a sense resistor. To turn off the IGBT, the driver uses a 2 A MOSFET output stage.

The 1EDI20I12SV is tailored for industrial drive applications using 1200 V power modules for currents up to 900 A, such as the EconoDUAL[™] 3 (up to 600 A). It is a single-channel IGBT driver IC based on Infineon's coreless transformer technology.

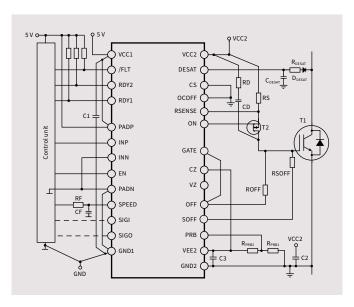
The driver meets today's long-term stability requirements for industrial applications. It is offered in a DSO-36 package with a package width of 300 mil. It is RoHS compliant, green, and halogen-free.

Features

- > 1200- V single-channel IGBT driver IC
- > Unique: precise dynamic gate current control
- Unique: selective short circuit protection for 3-level inverters
- Overcurrent protection for sense IGBTs and conventional IGBTs
- > Protection: DESAT, soft turn-off or two-level turn-off

Benefits

- Low EMI during low load conditions and high efficiency during high load conditions
- > Reduction or elimination of dV/dT filter











1EDI EiceDRIVER™ compact 150-mil and 300-mil

1200-V galvanically isolated single-channel wide body gate driver IC family

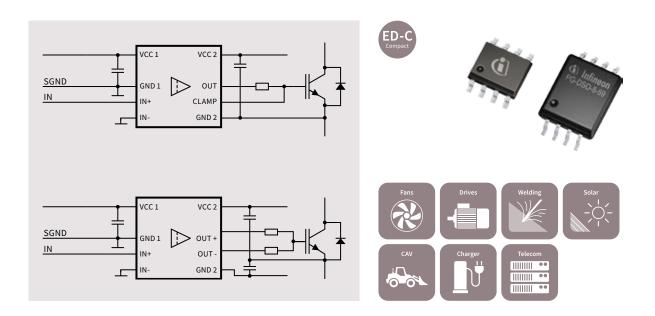
Our new 1EDI EiceDRIVER™ Compact family complements our extensive range of high-voltage driver ICs for a market that demands easy-to-use drivers with a small footprint for quick design-in cycles. The driver family is based on Infineon's coreless transformer technology, enabling a benchmark-setting minimum common mode transient immunity (CMTI) of 100 kV/µs with drive strengths of up to 6 A. They are ideal for IGBT-based applications such as photovoltaic string inverters, charge stations for electric vehicles, industrial drives, welding equipment, induction heating appliances and power supplies for servers and telecommunication systems

Features

- > Single-channel isolated high-voltage gate driver IC
- > 12 V input-to-output isolation voltage
- > Drives high-voltage power MOSFETs and IGBTs
- > Up to 6 A minimum peak rail-to-rail output
- > Separate source and sink outputs or active Miller clamp
- > DSO-8 300-mil-wide body package option with 8-mm creepage distance

Benefits

- > Best-in-class common mode transient immunity (CMTI): $100 \text{ kV/}\mu\text{s}$
- > Wide input operating range (3...17 V)
- > No voltage/signal adaptation between μC and driver necessary



For more information visit www.infineon.com/300mill and www.infineon.com/eicedriver-compact

1EDN and 2EDN EiceDRIVER™ families

Rugged, cool and fast, 1-channel low-side 4/8 A gate driver ICs

1-channel (1EDN) and 2-channel (2EDN) MOSFET gate driver ICs are the crucial link between control ICs and powerful MOSFET and GaN switching devices. Gate driver ICs enable high system level efficiencies, excellent power density and consistent system robustness.

Fast, precise, strong and compatible

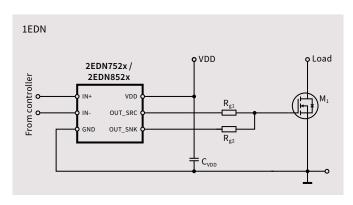
- Highly efficient SMPS enabled by 5 ns short slew rates and ±5 ns propagation delay precision for fast MOSFET and GaN switching
- Separate source and sink outputs simplify the application design
- Industry standard packages and pin-out ease system design upgrades

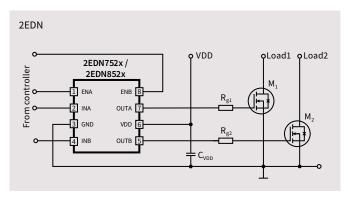
The new reference in ruggedness and low power dissipation

- > -10 V robustness of control and enable inputs provides crucial safety margin when driving pulse transformers
- > 5 A reverse output current robustness eliminates the need for Schottky switching diodes when driving MOSFETs in T0-220 and T0-247 packages
- > Cool driver ICs from true rail-to-rail low impedance output stages
- > 4 V and 8 V UVLO (under-voltage lockout) options for instant MOSFET protection during start-up and under abnormal conditions









For more information visit www.infineon.com/1edn









For more information visit www.infineon.com/2edn







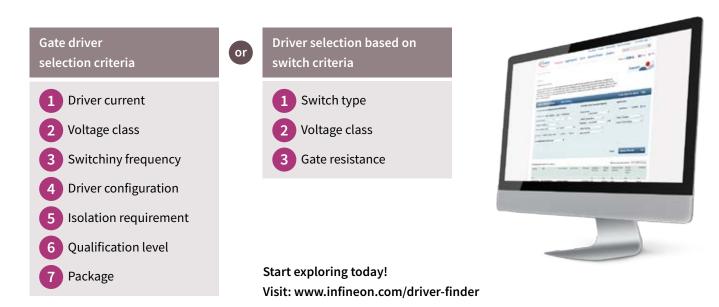


Infineon's powerful gate driver IC support

Useful links and helpful tools

Gate driver IC selection tool

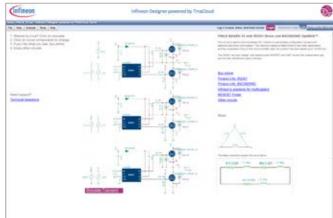
To simplify the gate driver selection process, Infineon offers an online easy-to-use gate driver selection tool. By selecting a few key parameters, the tool quickly guides you in finding the right driver for your application.



Infineon Designer

Select gate driver prototypes are available on **www.infineon.com/ifxdesigner**. Infineon Designer is an online prototyping engine combining analog and digital simulation functionalities in an Internet application. Requiring a web browser only, it is a perfect match for supporting customers in selecting the right product for a defined application.





Gate driver IC evaluation boards

EiceDRIVER™ evaluation boards are available on www.infineon.com/tool. The boards enable fast evaluation, prototyping and system design by demonstrating key characteristics and benefits of Infineon gate driver ICs.

Evaluation board



EVAL-6EDL04I06PT
Single EiceDRIVER™ with six 600 V
Trenchstop™ Infineon IGBTs in
full-bridge configuration



EVAL-6EDL04N02PR
Single EiceDRIVER™ with six 80 V
OptiMOS™ Infineon MOSFETs in
full-bridge configuration



EVAL-2EDL23I06PJSingle EiceDRIVER™ with two
600 V Infineon IGBTs in half-bridge
configuration



EVAL-2EDL23N06PJ
Single EiceDRIVER™ with two
600 V Infineon COOLMOS™
MOSFETs in half-bridge
configuration

Featured gate driver



6EDL04I06PT

LS-SOI 600 V three-phase gate driver IC with ultra-fast bootstrap diode and integrated protective features (interlock, over-current protection, fault reporting, and under-voltage lock out)



6EDL04N02PR

LS-SOI 200 V three-phase gate driver IC with ultra-fast bootstrap diode and integrated protective features (interlock, over-current protection, fault reporting, and under-voltage lock out)



2EDL23I06PJ

LS-SOI 600 V half-bridge gate driver IC with ultra-fast bootstrap diode and integrated protective features (interlock, over-current protection, fault reporting, and under-voltage lockout)



2EDL23N06PJ

LS-SOI 600 V half-bridge gate driver IC with ultra-fast bootstrap diode and integrated protective features (interlock, over-current protection, fault reporting, and under-voltage lockout)

Evaluation board



EVAL-1EDI60I12AF

Two EiceDRIVER™s with two 600 V TRENCHSTOP™ Infineon IGBTs in half-bridge configuration



EVAL-1ED020I12-BT

Two EiceDRIVER™s with two 1200 V Infineon IGBTs in half-bridge configuration



EVAL-1ED020I12-B2

Two EiceDRIVER™s with two 1200 V Infineon IGBT modules

Featured gate driver



1EDI60I12AF

Galvanically isolated CT 1200 V single-channel gate driver IC for high-voltage power IGBTs



1ED020I12-BT

Galvanically isolated CT 1200 V single-channel gate driver IC for high-voltage power IGBTs with integrated protective features (desaturation detection, two-level turn-off, active Miller clamping)



1ED020I12-B2

Galvanically isolated CT 1200 V single-channel gate driver IC for high-voltage power IGBTs with integrated protective features (desaturation detection, two-level turn-off, active Miller clamping)

Contact your local Infineon sales team for evaluation board availability information.

Gate driver IC chips for multi-chip packages

Infineon offers gate driver IC chips to address the on-going trend of integrating the driver, power stages, controllers and other components into a smaller, more efficient single package.

					Technology	Current amplifier	Current sense	Enable	Fault reporting	Integrated bootstrap diode	Over-current protection	Programmable shutdown	Self-oscillating	Separate pin for logic ground	Shoot-through protection	Shutdown	Under-voltage lockout	Chip
Driver configuration	Voltage class [V]	l _{o+} /l _{o-} typ [mA]	Typ. prop. delay: off/on [ns]	Base PN								ure age						
			105/250	IR2117	JI												✓	✓
		250/500	150/200	IR2127	JI		✓		✓		✓					✓	✓	✓
Single high-side	600		150/200	IR2128	JI		✓		✓		✓						✓	✓
		200/500	105/125	IRS211(7,8)	JI											✓	✓	✓
		290/600	150/150	IRS2127	JI		√		✓		✓						√	V
	1200	2000/2500	225/280	IR2213	JI									✓			√	√
		210/360	150/160	IR2101	JI												√	√
			130/135	IRS2112	JI									√		√	✓	✓
		290/600	150/160	IRS2101	JI											V	√	√
			200/220	IRS2106	JI												√	√
High-side and	600	1900/2300	220/180	IRS2181	JI											/	√	V
low-side			94/120	IR2113	JI									V			✓	✓
		2500/2500	120/130	IRS2113	JI									V		/	√	V
		4000/4000	170/170	IRS2186	JI												√	√
	500	2500/2500	120/130	IRS2110	JI									V			√	1
		1000/1000	60/60	IRS2011	JI												√	√
	200	3000/3000	65/95	IR2010	JI									V			√	1
			33/33	IR21531	JI							/	√		√	√	✓	1
		180/260	na	IRS2153(1)D	JI							√	✓		✓	<i>\</i>	√	√
			150/150	IRS2304	JI										✓		√	√
			130/130	IRS2103	JI										√		√	✓
			150/680	IRS2104	JI										✓	/	√	√
Half-bridge	600	290/600	150/750	IRS2111	JI										✓	V	∨	√
Tidli bilage	- 000	230/000	150/150	IRS2111	JI										✓		✓	✓
			200/220	IRS2308	JI										V		V ✓	V
			200/750	IRS2109	JI										✓	/	✓	✓
			220/180	IRS2183	JI										./		√	✓
		1900/2300	270/680	IRS2184	JI										√	/	√	✓
	1200	250/500	700/750	IR2233	JI	√			√		√			√	V	V ✓	V ✓	V
	1200	250/500		6ED003L06-F2	SOI	,		√	✓		✓			✓		·	✓	✓
		165/375	490/530	6EDL04I06(N,P)	SOI			V	V	√	V			V			V ✓	V
		103/313	530/530	6EDL04N06P	SOI			✓	✓	✓	✓			✓			✓	✓
			330/330	IR2136	JI			V	V	V	V			V			V	V
			400/425	IR21363	JI			✓	✓		✓			✓			✓	✓
Three-phase	600		100/420	IR21368	JI			√	√		√			✓			V	√
	000	200/350	530/500	IR21364	JI			✓	✓		✓ ✓			✓			✓	✓
			330/300	IRS2336D	JI			V	✓	√	✓ ✓			✓ ✓			✓	✓
			530/530	IRS23364D	JI			✓	✓	✓	✓ ✓			✓			✓	✓
			425/675	IR213(0,2)	JI	√		V	✓	V	✓ ✓			✓			✓	✓ ✓
		250/500	700/750	IR213(0,2)	JI	✓			✓		✓			✓		./	✓	✓
			100/150	IKZ133	JI	V			V		V			V			V	V

Where to buy

Infine on distribution partners and sales offices: www.infineon.com/WhereToBuy

Service hotline

Infineon offers its toll-free 0800/4001 service hotline as one central number, available 24/7 in English, Mandarin and German.

- > Germany 0800 951 951 951 (German/English)
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